

ABSTRACT

A multi-chip stack flip-chip package comprises a substrate and a chip assembly on the substrate. The chip assembly includes a dummy chip and a flip chip. The dummy chip has a redistribution layer that has a plurality of bump pads for mounting the flip chip, a plurality of peripheral pads for electrically connecting to the substrate, and a plurality of integrated circuit traces connecting the bump pads with the peripheral pads. The dummy chip is disposed between the flip chip and the substrate as an electrically connecting interface between the flip chip and the substrate for multi-chip flip-chip stack and fine pitch flip-chip mounting.